AMENDMENTS TO THE CLAIMS

Listing of the Claims:

Claims 1-36 (Cancelled)

Claims 37-52 (Cancelled)

- 53. (Cancelled)
- 54. (Cancelled)
- 55. (Currently amended) The liquid thermosetting ink-jet ink according to claim [[54]] <u>68</u>, wherein said curing agent is selected from a group consisting of urea derivatives, imidazoles, dicyandiamide, inorganic boron halides, their precursors and/or any mixture thereof.
- 56. (Previously presented) The liquid thermosetting ink-jet ink according to claim [[53]] <u>68</u>, wherein said inert <u>particle filler</u> is selected from a group consisting of barium sulfate, talc, silica, kaolin, mica and glass.
- 57. (Cancelled).
- 58. (Currently amended) The liquid thermosetting ink-jet ink according to claim 57, wherein the epoxy compounds are selected from group consisting of bisphenol S epoxy resins, heterocyclic epoxy resins, bisphenol A epoxy resins, hydrogenated bisphenol A epoxy resins, bisphenol F epoxy resins, Novolak epoxy resins, Novolak epoxy resins of bisphenol A, rubber-modified epoxy resins, or a mixture thereof.
- 59. (Currently amended) The liquid thermosetting ink-jet ink according to claim 53, additionally comprising monomers and/or oligomers selected from styrene, acrylic or methacrylic acid and esters thereof; acrylated or methacrylated epoxies; acrylated or methacrylated urethanes; wherein the unsaturated monomers are selected from (meth)acrylates, acrylated DGEBA epoxy, acrylated Novolac epoxy, acrylated polyurethane, or

Application No.: 10/762,515 Docket No.: 1267-267

any combination thereof.

60. (Currently amended) The liquid thermosetting ink-jet ink according to claim [[53]] <u>68</u>, especially adapted for solder mask in printed circuit boards.

- 61. (Currently amended) The liquid thermosetting ink-jet ink according to claim [[53]] <u>68</u>, especially adapted for bonding devices or components in electronic manufacturing.
- 62. (Previously presented) The liquid thermosetting ink-jet ink according to claim [[53]] <u>68</u>, especially adapted for printing of layers in the manufacturing of passive component capacitors and/or resistors.
- 63. (Previously presented) The liquid thermosetting ink-jet ink according to claim [[53]] <u>68</u>, especially—adapted for direct printing of conductive lines and features such as pads and/or bumps.
- 64. (Currently amended) The liquid thermosetting ink-jet ink according to claim [[53]] <u>68</u>, additionally comprising impact modifiers and/or flexibilizers having rubbery moieties or blocks in their chain.
- 65. (Currently amended) The liquid thermosetting ink-jet ink according to claim 53, wherein the impact modifiers and/or flexibilizers are selected from elastomeric, oligomers comprising side or end groups, selected from amines, epoxies, hydroxyls, wherein said functional terminated rubbers or rubber-like compositions comprising polybutadienes, polyisoprenes, polysulfides, polyurethanes, hydrogenated polybutadienes and/or polyisoprenes, ethylene-propylene copolymers, soft polyacrylate esters, polydimethyl siloxane, zirconate, titanate, aluminate or any mixture thereof acrylonytrile-butadiene, styrene-butadiene, styrene-acrylate, soft polyacrylate esters, hydrogenataed polybutadienes, polyisoprenes, ethylene-propylene copolymers, polydimethyl siloxane elastomers, polysulfide, polyurethane, or any mixture thereof.
- 66. (Currently amended) The liquid thermosetting ink-jet ink according to claim [[53]] <u>68</u>, additionally comprising mineral fillers, having maximal particle size of about 2 micron in the final ink; wherein concentration ranges between about 1 to 30 % by weight.

Application No.: 10/762,515 Docket No.: 1267-267

67. (Previously presented) The liquid thermosetting ink-jet ink according to claim [[53]] <u>68</u>, additionally comprising additives selected from surface active agents and/or colloid stabilizers, rheology modifiers, pigments and dyes, matting agents, solvents; co-solvents, diluents or any mixture thereof.

- 68. (New) A micron liquid thermosetting ink-jet ink comprising:
- (a) at least one solid latent curing agent comprising an inert filler having maximal particle size of less than 2 microns; said curing agent is layered on the surface of said inert particle, deposited as crystals on its surface, impregnated in its porosity or dispersed in small crystals in a dispersing agent layer on or in the inert particle surface; and
- (b) one or more epoxy resin; said ink-jet ink being characterized by a viscosity lower than 50 Cps at application temperature; a surface tension lower than 80 dyn/cm at application temperature; and a glass transition temperature, in the cured form, of greater than 120°C.